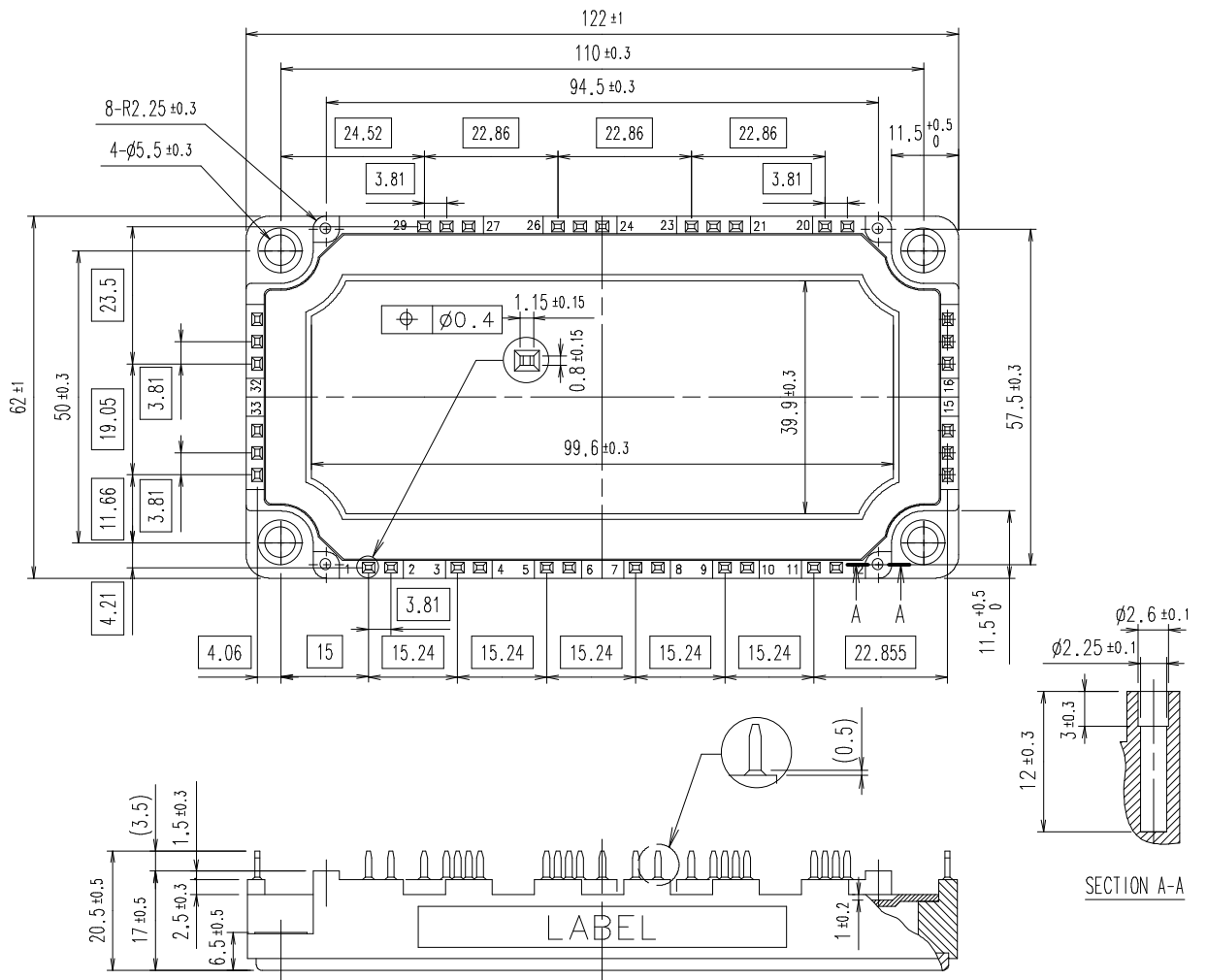


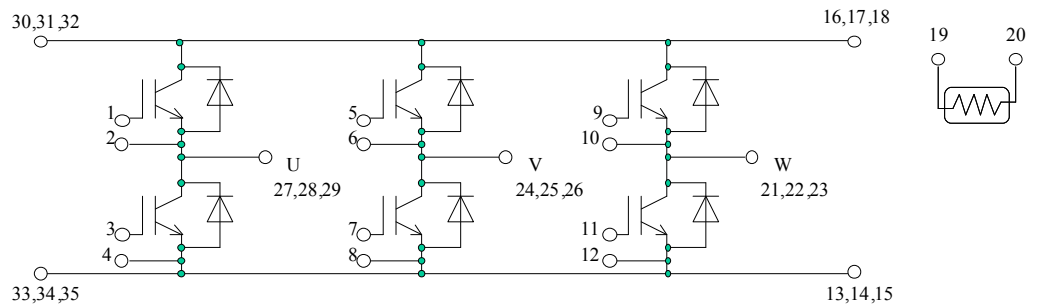
6MBI100U4B-120-50 (RoHS compliant product)

1. Outline Drawing (Unit : mm)



□ shows theoretical dimension.
 () shows reference dimension.

2. Equivalent circuit



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3. Absolute Maximum Ratings (at Tc= 25°C unless otherwise specified)

Items	Symbols	Conditions	Maximum Ratings	Units
Collector-Emitter voltage	V _{CES}		1200	V
Gate-Emitter voltage	V _{GES}		±20	V
Collector current	I _c	Continuous	T _c =25°C 150 T _c =80°C 100	A
	I _{cp}	1ms	T _c =25°C 300 T _c =80°C 200	
	-I _c		100	
	-I _c pulse	1ms	200	
Collector Power Dissipation	P _c	1 device	520	W
Junction temperature	T _j		+150	°C
Storage temperature	T _{stg}		-40 to +125	
Isolation voltage	Viso	AC : 1min.	2500	VAC
Screw Torque	Mounting (*3)	-	3.5	N m

(*1) All terminals should be connected together when isolation test will be done.

(*2) Two thermistor terminals should be connected together, each other terminals should be connected together and shorted to base plate when isolation test will be done.

(*3) Recommendable Value : 2.5 to 3.5 Nm (M5)

4. Electrical characteristics (at Tj= 25°C unless otherwise specified)

Items	Symbols	Conditions	Characteristics			Units		
			min.	typ.	max.			
Inverter	Zero gate voltage collector current	ICES	VCE=1200V VGE=0V	-	-	1.0	mA	
	Gate-Emitter leakage current	IGES	VCE=0V VGE=±20V	-	-	200	nA	
	Gate-Emitter threshold voltage	VGE(th)	VCE=20V Ic=100mA	4.5	6.5	8.5	V	
	Collector-Emitter saturation voltage	VCE(sat) (terminal)	Ic=100A VGE=15V	Tj=25°C	-	2.25	② 2.60	V
				Tj=125°C	-	2.45	-	
		VCE(sat) (chip)	Tj=25°C	-	1.90	2.05		
			Tj=125°C	-	2.10	-		
	Input capacitance	Cies	VCE=10V, VGE=0V, f=1MHz	-	11	-	nF	
	Turn-on time	ton	Vcc=600V	-	0.32	1.20	us	
		tr	Ic=100A	-	0.10	0.60		
		tr(i)	VGE=±15V	-	0.03	-		
	Turn-off time	toff	RG=5.6Ω	-	0.41	1.00	us	
		tf		-	0.07	0.30		
	Forward on voltage	VF (terminal)	IF=100A VGE=0V	Tj=25°C	-	2.00	② 2.30	V
Tj=125°C				-	2.10	-		
VF (chip)		Tj=25°C	-	1.65	1.80			
		Tj=125°C	-	1.75	-			
Reverse recovery time	trr	IF=100A	-	-	0.35	us		
Lead resistance, terminal-chip (*4)	R lead		-	3.40	-	mΩ		
Thermistor	Resistance	R	T=25°C	-	5000	-	Ω	
			T=100°C	465	495	520		
	B value	B	T=25/50°C	3305	3375	3450	K	

(*4) Biggest internal terminal resistance among arm.

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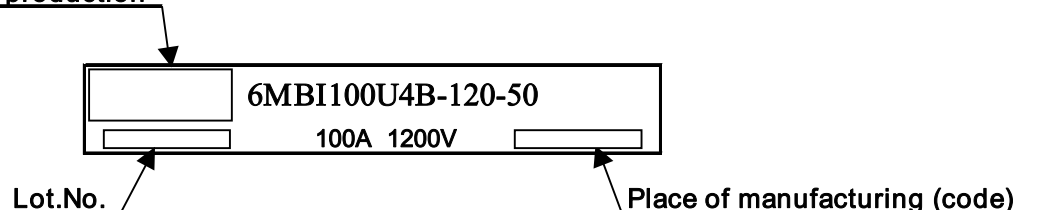
5. Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance(1device)	Rth(j-c)	IGBT	-	-	0.24	°C/W
		FWD	-	-	0.39	
Contact Thermal resistance (1 device) (*5)	Rth(c-f)	with Thermal Compound	-	0.05	-	

(*5) This is the value which is defined mounting on the additional cooling fin with thermal compound.

6. Indication on module

Logo of production



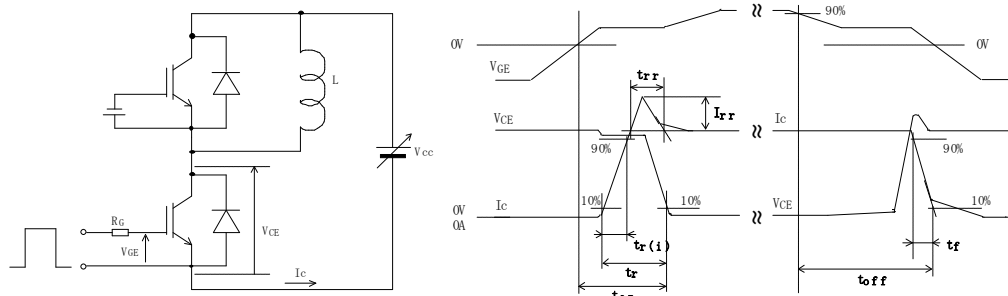
7. Applicable category

This specification is applied to IGBT-Module named 6MBI100U4B-120-50.

8. Storage and transportation notes

- The module should be stored at a standard temperature of 5 to 35°C and humidity of 45 to 75% . Be careful to solderability of the terminals if the module has passed over one year from manufacturing date, under the above storage condition.
- Store modules in a place with few temperature changes in order to avoid condensation on the module surface.
- Avoid exposure to corrosive gases and dust.
- Avoid excessive external force on the module.
- Store modules with unprocessed terminals.
- Do not drop or otherwise shock the modules when transporting.

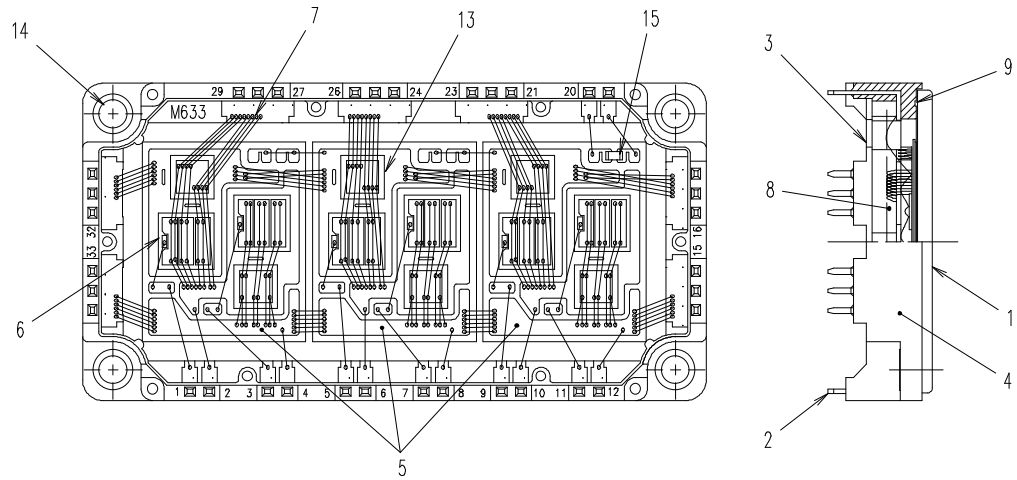
9. Definitions of switching time



10. Packing and Labeling

- Display on the packing box
- Logo of production
 - Type name
 - Lot No
 - Products quantity in a packing box

11. List of material (材料リスト)



(Total weight of soldering material(typ) : 8.8 g)

No.	Parts	Material (main)	Ref.
1	Base Plate	Cu	Ni plating
2	Terminal	Cu	Ni plating (Internal)
			Lead free solder plating (External)
3	Cover	PPS resin	UL 94V-0
4	Case	PPS resin	UL 94V-0
5	Isolation substrate	Al ₂ O ₃ + Cu	
6	IGBT chip	Silicon	
7	Wiring	Aluminum	
8	Silicone Gel	Silicone resin	
9	Adhesive	Silicone resin	
10	Solder (Under chip)	Sn/Ag base	(Not drawn in above)
11	Solder (Under Isolation substrate)	Sn/Ag base	(Not drawn in above)
12	Label	Paper	(Not drawn in above)
13	FWD chip	Silicon	
14	Ring	Fe	Trivalent Chromate treatment
15	Thermistor	Lead glass	

12. RoHS Directive Compliance (RoHS 指令適用について)

本IGBTモジュールは富士電機デバイステクノロジーが発行しているRoHSに関する資料MS5F6209を適用する。
日本語版(MS5F6212)は参考資料とする。

The document (MS5F6209) about RoHS that Fuji Electric Device Technology issued is applied to this IGBT Module. The Japanese Edition(MS5F6212) is made into a reference grade.

13. Reliability test results

Reliability Test Items

Test categories	Test items	Test methods and conditions	Reference norms EIAJ ED-4701 (Aug.-2001 edition)	Number of sample	Acceptance number
Mechanical Tests	1 Terminal Strength (Pull test)	Pull force : 20N Test time : 10±1 sec.	Test Method 401 Method I	5	(0 : 1)
	2 Mounting Strength	Screw torque : 2.5 ~ 3.5 N·m (M5) Test time : 10±1 sec.	Test Method 402 method II	5	(0 : 1)
	3 Vibration	Range of frequency : 10 ~ 500Hz Sweeping time : 15 min. Acceleration : 100m/s ² Sweeping direction : Each X,Y,Z axis Test time : 6 hr. (2hr./direction)	Test Method 403 Reference 1 Condition code B	5	(0 : 1)
	4 Shock	Maximum acceleration : 5000m/s ² Pulse width : 1.0msec. Direction : Each X,Y,Z axis Test time : 3 times/direction	Test Method 404 Condition code B	5	(0 : 1)
	5 Solderability	Solder temp. : 245±5 °C Immersion time : 5±0.5sec. Test time : 1 time Solder Alloy : Sn-Ag-Cu Each terminal should be Immersed in solder within 1~1.5mm from the body.	Test Method 303	5	(0 : 1)
	6 Resistance to Soldering Heat	Solder temp. : 260±5 °C Immersion time : 10±1sec. Test time : 1 time Each terminal should be Immersed in solder within 1~1.5mm from the body.	Test Method 302 Condition code A	5	(0 : 1)
Environment Tests	1 High Temperature Storage	Storage temp. : 125±5 °C Test duration : 1000hr.	Test Method 201	5	(0 : 1)
	2 Low Temperature Storage	Storage temp. : -40±5 °C Test duration : 1000hr.	Test Method 202	5	(0 : 1)
	3 Temperature Humidity Storage	Storage temp. : 85±2 °C Relative humidity : 85±5% Test duration : 1000hr.	Test Method 103 Test code C	5	(0 : 1)
	4 Unsaturated Pressurized Vapor	Test temp. : 120±2 °C Test humidity : 85±5% Test duration : 96hr.	Test Method 103 Test code E	5	(0 : 1)
	5 Temperature Cycle	Test temp. : ┌ Low temp. -40±5 °C └ High temp. 125 ±5 °C RT 5 ~ 35 °C Dwell time : High ~ RT ~ Low ~ RT 1hr. 0.5hr. 1hr. 0.5hr. Number of cycles : 100 cycles	Test Method 105	5	(0 : 1)
	6 Thermal Shock	Test temp. : ┌ High temp. 100 ⁺⁰ -5 °C └ Low temp. 0 ⁺⁵ -0 °C Used liquid : Water with ice and boiling water Dipping time : 5 min. par each temp. Transfer time : 10 sec. Number of cycles : 10 cycles	Test Method 307 method I Condition code A	5	(0 : 1)

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Reliability Test Items

Test categories	Test items	Test methods and conditions	Reference norms EIAJ ED-4701 (Aug.-2001 edition)	Number of sample	Acceptance number
Endurance Tests	1 High temperature Reverse Bias (for Collector-Emitter)	Test temp. : $T_a = 125 \pm 5 \text{ }^\circ\text{C}$ $(T_j \leq 150 \text{ }^\circ\text{C})$ Bias Voltage : $V_C = 0.8 \times V_{CES}$ Bias Method : Applied DC voltage to C-E $V_{GE} = 0V$ Test duration : 1000hr.	Test Method 101	5	(0 : 1)
	2 High temperature Bias (for gate)	Test temp. : $T_a = 125 \pm 5 \text{ }^\circ\text{C}$ $(T_j \leq 150 \text{ }^\circ\text{C})$ Bias Voltage : $V_C = V_{GE} = +20V$ or $-20V$ Bias Method : Applied DC voltage to G-E $V_{CE} = 0V$ Test duration : 1000hr.	Test Method 101	5	(0 : 1)
	3 Temperature Humidity Bias	Test temp. : $85 \pm 2 \text{ }^\circ\text{C}$ Relative humidity : $85 \pm 5\%$ Bias Voltage : $V_C = 0.8 \times V_{CES}$ Bias Method : Applied DC voltage to C-E $V_{GE} = 0V$ Test duration : 1000hr.	Test Method 102 Condition code C	5	(0 : 1)
	4 Intermitted Operating Life (Power cycle) (for IGBT)	ON time : 2 sec. OFF time : 18 sec. Test temp. : $\Delta T_j = 100 \pm 5 \text{ deg}$ $T_j \leq 150 \text{ }^\circ\text{C}, T_a = 25 \pm 5 \text{ }^\circ\text{C}$ Number of cycles : 15000 cycles	Test Method 106	5	(0 : 1)

Failure Criteria

Item	Characteristic	Symbol	Failure criteria		Unit	Note	
			Lower limit	Upper limit			
Electrical characteristic	Leakage current	ICES	-	USL×2	mA		
		±IGES	-	USL×2	μA		
	Gate threshold voltage	VGE(th)	LSL×0.8	USL×1.2	mA		
	Saturation voltage	VCE(sat)	-	USL×1.2	V		
	Forward voltage	VF	-	USL×1.2	V		
	Thermal resistance	IGBT	Δ VGE or Δ VCE	-	USL×1.2	mV	
		FWD	Δ VF	-	USL×1.2	mV	
	Isolation voltage	Viso	Broken insulation		-		
Visual inspection	Visual inspection Peeling Plating and the others	-	The visual sample		-		

LSL : Lower specified limit.
 USL : Upper specified limit.

Note Each parameter measurement read-outs shall be made after stabilizing the components at room ambient for 2 hours minimum, 24 hours maximum after removal from the tests. And in case of the wetting tests, for example, moisture resistance tests, each component shall be made wipe or dry completely before the measurement.

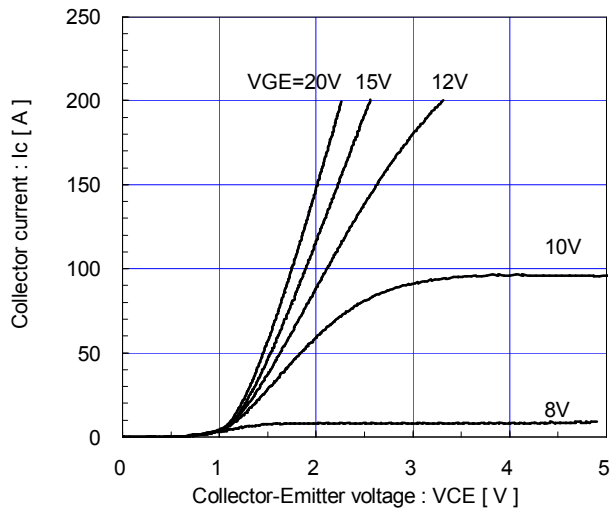
Reliability Test Results

Test categories	Test items	Reference norms EIAJ ED-4701 (Aug.-2001 edition)	Number of test sample	Number of failure sample
Mechanical Tests	1 Terminal Strength (Pull test)	Test Method 401 Method I	5	0
	2 Mounting Strength	Test Method 402 method II	5	0
	3 Vibration	Test Method 403 Condition code B	5	0
	4 Shock	Test Method 404 Condition code B	5	0
	5 Solderability	Test Method 303	5	0
	6 Resistance to Soldering Heat	Test Method 302 Condition code A	5	0
Environment Tests	1 High Temperature Storage	Test Method 201	5	0
	2 Low Temperature Storage	Test Method 202	5	0
	3 Temperature Humidity Storage	Test Method 103 Test code C	5	0
	4 Unsaturated Pressurized Vapor	Test Method 103 Test code E	5	0
	5 Temperature Cycle	Test Method 105	5	0
	6 Thermal Shock	Test Method 307 method I Condition code A	5	0
Endurance Tests	1 High temperature Reverse Bias (for Collector-Emitter)	Test Method 101	5	0
	2 High temperature Bias (for gate)	Test Method 101	5	0
	3 Temperature Humidity Bias	Test Method 102 Condition code C	5	0
	4 Intermitted Operating Life (Power cycling) (for IGBT)	Test Method 106	5	0

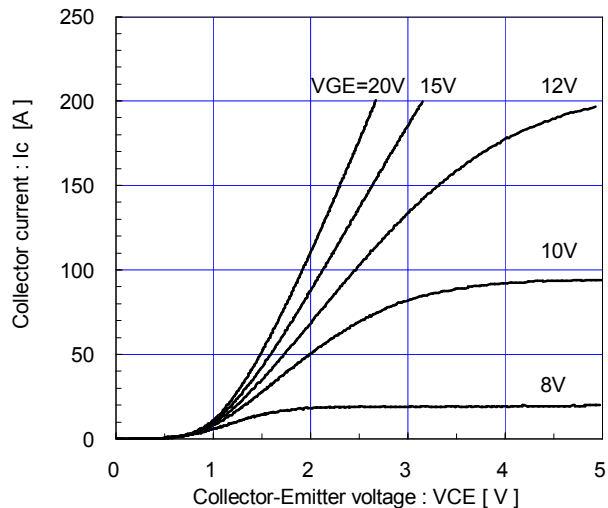
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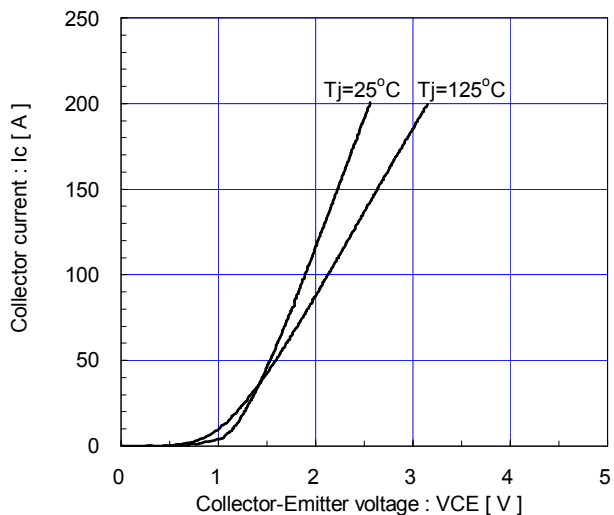
Collector current vs. Collector-Emitter voltage (typ.)
T_j=25°C / chip



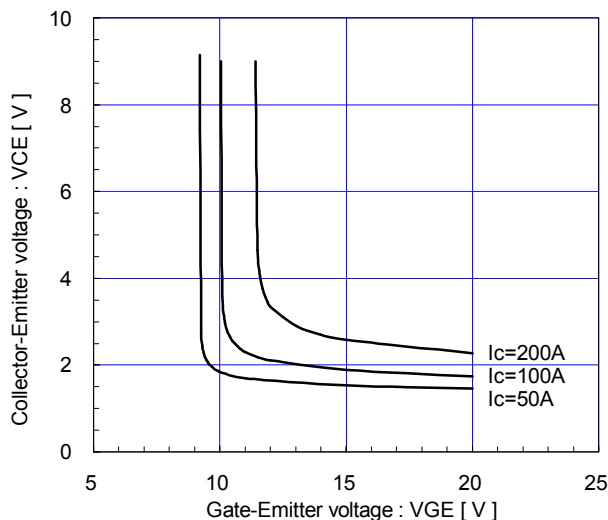
Collector current vs. Collector-Emitter voltage (typ.)
T_j=125°C / chip



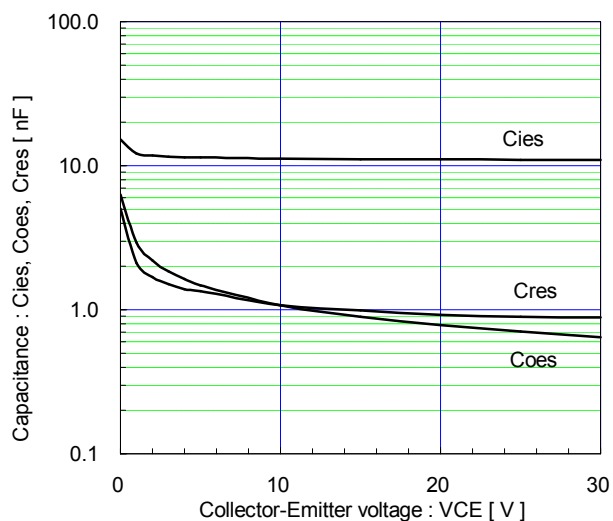
Collector current vs. Collector-Emitter voltage (typ.)
VGE=15V / chip



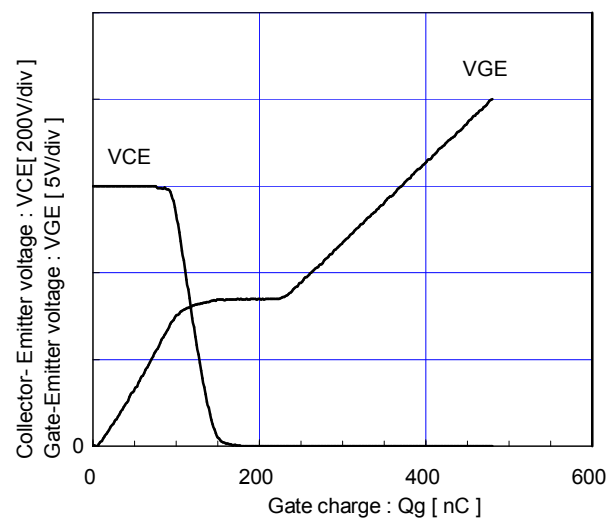
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)
T_j=25°C / chip



Capacitance vs. Collector-Emitter voltage (typ.)
VGE=0V, f=1MHz, T_j=25°C

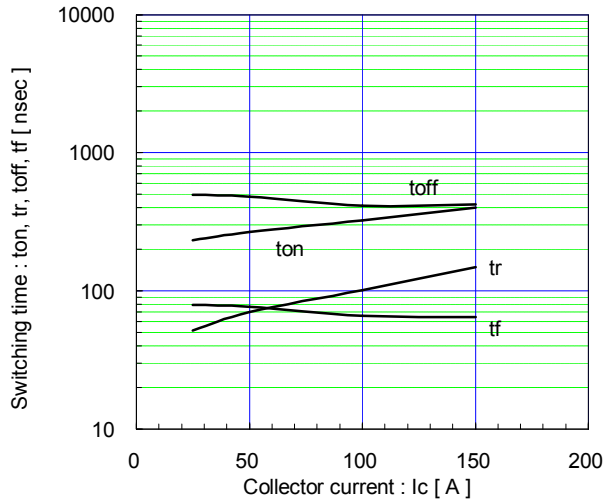


Dynamic Gate charge (typ.)
V_{cc}=600V, I_c=100A, T_j=25°C

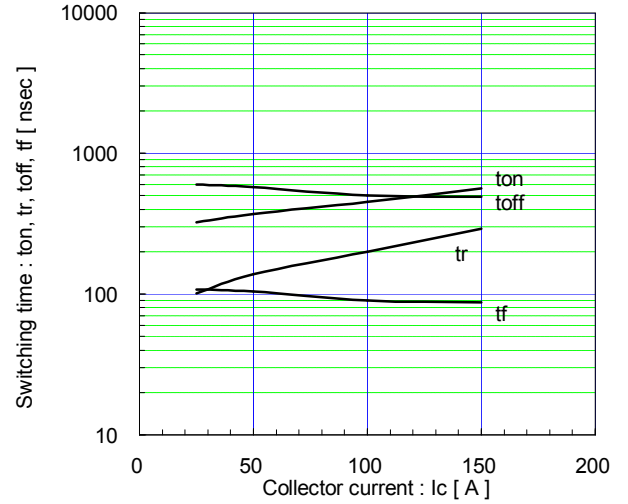


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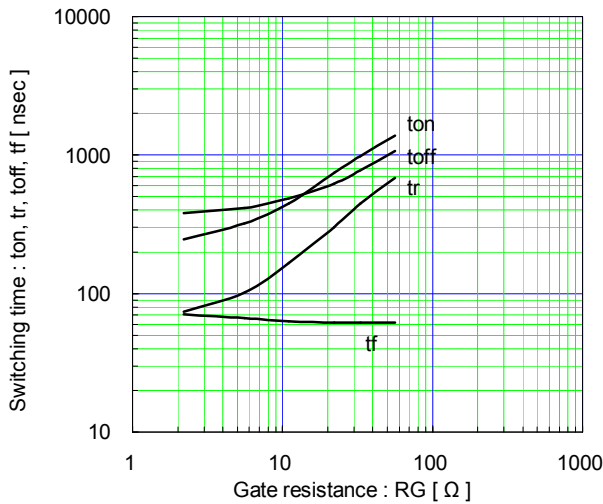
Switching time vs. Collector current (typ.)
 $V_{CC}=600V, V_{GE}=\pm 15V, R_G=5.6\Omega, T_j=25^\circ C$



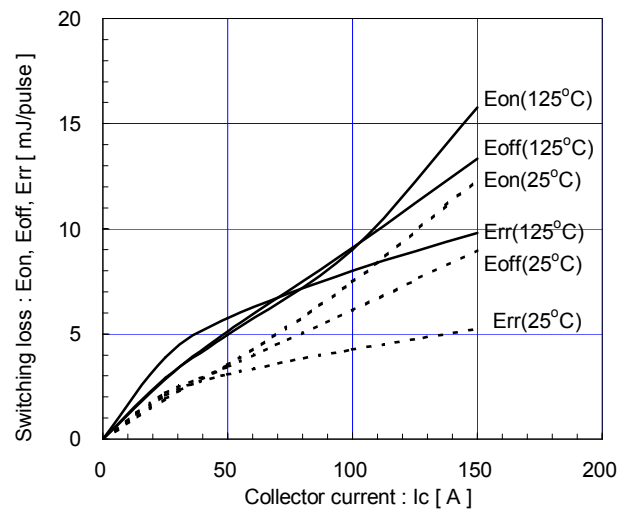
Switching time vs. Collector current (typ.)
 $V_{CC}=600V, V_{GE}=\pm 15V, R_G=5.6\Omega, T_j=125^\circ C$



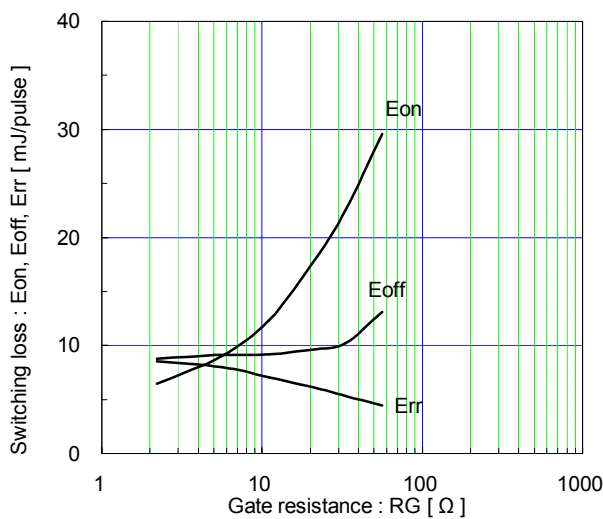
Switching time vs. Gate resistance (typ.)
 $V_{CC}=600V, I_C=100A, V_{GE}=\pm 15V, T_j=25^\circ C$



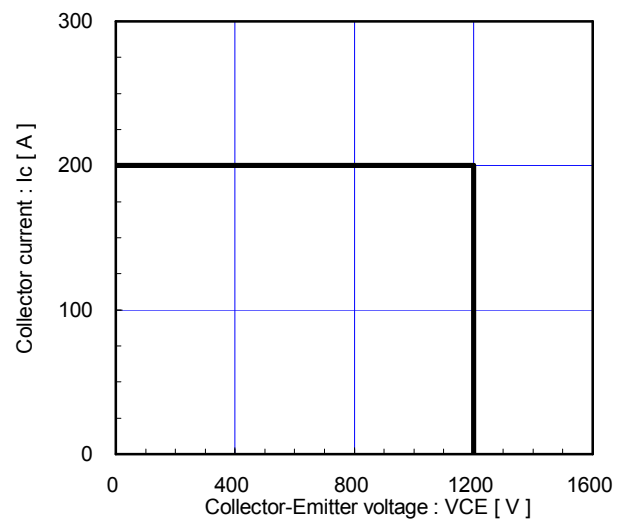
Switching loss vs. Collector current (typ.)
 $V_{CC}=600V, V_{GE}=\pm 15V, R_G=5.6\Omega$



Switching loss vs. Gate resistance (typ.)
 $V_{CC}=600V, I_C=100A, V_{GE}=\pm 15V, T_j=125^\circ C$

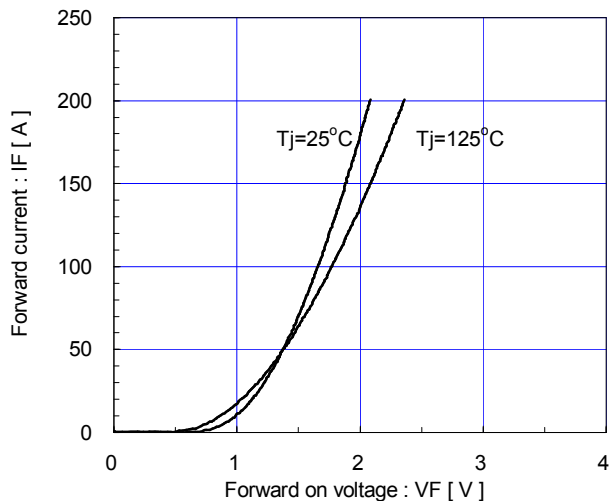


Reverse bias safe operating area (max.)
 $+V_{GE}=15V, -V_{GE} \le 15V, R_G \ge 5.6\Omega, T_j \le 125^\circ C$

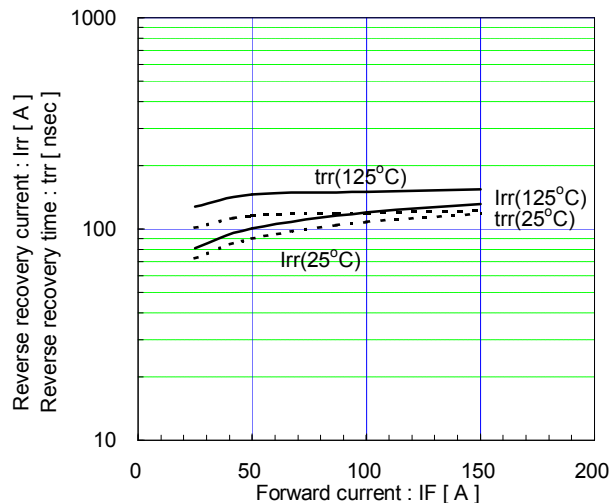


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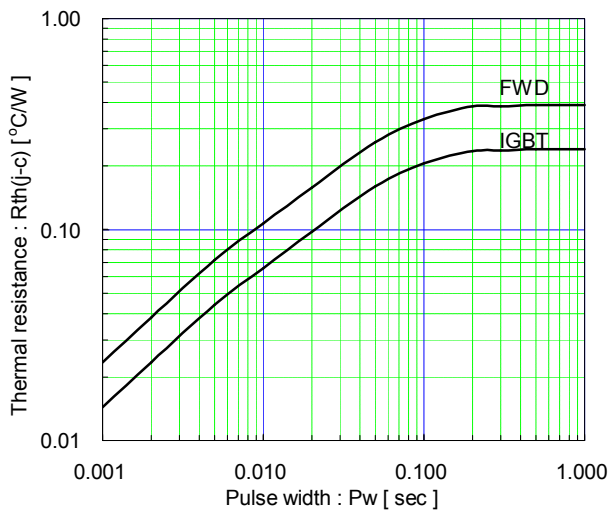
Forward current vs. Forward on voltage (typ.)
chip



Reverse recovery characteristics (typ.)
Vcc=600V, VGE=±15V, RG=5.6Ω



Transient thermal resistance (max.)



[Thermistor]

Temperature characteristic (typ.)

